4.4. WAFER TRANSPORT SYSTEM:

-1. Sending Station-->Coating	Indexing Elevator, Vacuum chuck, & Shuttle Mechanism
-2. Coating-->Baking	Shuttle Mechanism, Vacuum chuck, & Walking Beam
-3. Baking-->Receiving Unit	Walking Beam, Vacuum chuck & Indexing Elevator

4.5. CONTROL UNIT:

-1. Microprocessor	INTEL8085 (one main and two sub CPUs)
-2. Speed	100-9000 rpm(4") or 8000rpm(6") ± .15% (between 50 - 1990rpm) and ± .1% (between 2000-6000 rpm)
-3. Acceleration	Alarm for speed ±3% of rpm (speed higher than 300 rpm) max. rate .1 sec for 0 to 5000 rpm. (programmable in increments of .1 sec.)
-4. Process	20 steps, 8 or16 recipes
-5. Temperature Control	±1℃ uniformity with alarm setting of ± 3℃
-6. Spinning Time	0-99 sec. programmable
-7. Dispensing Time	0-99 sec. programmable
-8. Baking Time	0-999 sec. programmable
-9. Process Display	Back-lit LCD
-10. Interface	RS232C ports (software optional)

5. OPTIONS

-1. SOG FILTER :	.22μm Fluoropore Filter
-2. CHEMICAL CABINET:	Remote 5 gallon capacity
-3. BACK SIDE RINSE (EDGE BEAD REMOVAL):	2 Nozzles
-4. SOLVENT FILTER:	.22μm filter (Millipore Fluorex CWFG00403or Wafergard WGFG04HP6)
-5. CUP EXHAUST STABILIZER:	A transvector connection draws exhaust fumes which are regulated by a sequential damper. A manometer monitors exhaust level.
-6. GAS LINE FILTER:	Millipore Wafergard GTL WGFG01D 0.22 μm filter.